APPENDIX I

AMENDED CLAIMS WITH AMENDMENTS INDICATED THEREIN
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9. (Amended) A method of mounting an electronic component in which a plurality of parts cassettes respectively accommodating different types of electronic components are moved by a component feeding unit to a component [pick-up] feeding position in a mounting order for feeding electronic components, and a plurality of component suction nozzles are successively moved along a circular track from [the] a component pick-up position above the component feeding position, where the component suction nozzle picks up the electronic component, to a posture recognizing position, where the posture of the electronic component held with the component suction nozzle is detected, [based on which the position and angle of the electronic component in relation to a predetermined position on a circuit substrate are corrected,] and further to a component mounting position, where the picked-up electronic component is mounted on the [predetermined position on the] circuit substrate, comprising[the steps of]:

obtaining data on an amount of displacement of the component from a prescribed holding position of the component suction nozzle corresponding to each of the parts cassettes based on posture recognition results detected at the posture recognizing position; and

adjusting [a] the component feeding position of [the] a subsequently-fed electronic component to more accurately correspond to the component pick-up position based on [this] said data on the amount of displacement [amount data].

10. (Amended) The method of mounting an electronic component according to claim 9, [in which] wherein at least one of a [the] position of the

component feeding unit [or the] and a placing position of the parts cassettes onto the component feeding unit is adjusted based on [the] said data on the amount of displacement [amount data].

11. (Amended) The method of mounting an electronic component according to claim 9, [in which] wherein the component feeding position from each of the parts cassettes toward the component pick-up position is adjusted based on the displacement amount data.

12. (Amended) A device for mounting an electronic component in which a plurality of parts cassettes respectively accommodating different types of electronic components are moved by a component feeding unit to a component [pick-up] feeding position in a mounting order for feeding electronic components, and a plurality of component suction nozzles are successively moved along a circular track from [the] a component pick-up position above the component feeding position, where the component suction nozzle picks up the electronic component, to a posture recognizing position, where the posture of the electronic component held with the component suction nozzle is detected, [based on which the position and angle of the electronic component in relation to a predetermined position on a circuit substrate are corrected,] and further to a component mounting position, where the picked-up electronic component is mounted on the [predetermined position on the] circuit substrate, comprising:

[a] displacement amount data processing means for obtaining data on an amount of displacement of the electronic component from a prescribed holding position of the suction nozzle corresponding to each of the parts cassettes based on posture recognition results detected at the posture recognizing position, and

[a] drive means for moving at least one of the component feeding unit [or] and the parts cassette [so as] in a direction to adjust the component feeding

position to more accurately correspond to the component pick-up position [in a direction] for correcting the amount of displacement of the electronic component which is obtained from the displacement amount data for a subsequently-fed electronic component.